Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1012073	(multi multilayer wiring interconnection interconnect interconnting printed circuit) with (board carrier subtrate structure)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 12:46
L2	394659	(chip die semiconductor electronic component passive flipchip (flip adj chip) bga) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 12:54
L3	77300	(support frame supporting supported metal conductive cobalt nickel ni copper cu aluminum titanium ti alsi alsic tungsten w zirconium chromium cr zr fe iron) with (substrate carrier support frame) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 12:54
L4	189557	(support frame supporting supported metal conductive cobalt nickel ni copper cu aluminum titanium ti alsi alsic tungsten w zirconium chromium cr zr fe iron) with (substrate carrier support frame) and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 12:55
L5	312600	(chip die semiconductor electronic component passive flipchip (flip adj chip) bga) with 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 12:54
L6	36374	(support frame supporting supported metal conductive cobalt nickel ni copper cu aluminum titanium ti alsi alsic tungsten w zirconium chromium cr zr fe iron) with (substrate carrier support frame) with 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 12:55
L7	3322	(barrier) and (terminal pad electrode) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 12:57
L8	1634	(package packaging packaged) and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 12:58